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ONS00149  
09/817,330

IN THE TITLE

Please amend the title as follows.

METHOD OF MAKING A LEAD-FREE INTEGRATED CIRCUIT PACKAGE  
AND METHOD

CLAIM OBJECTION

Claims 19-31 are objected to on the basis that "first surface" in claim 19 should be "second surface" and "second surface" in claim 20 should be "first surface". Claims 19-25 and 29 are modified as shown below to incorporate the language preferred by the examiner.

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